

ABSTRACT**VACUUM CHAMBER ARRANGEMENT AND METHOD FOR PROCESSING A
SUBSTRATE**

In various embodiments, a vacuum chamber arrangement (100) is provided. The vacuum chamber arrangement (100) having a vacuum chamber (102); at least one processing region (202b) which is arranged in the vacuum chamber (102); and a substrate holding arrangement (104) for transporting and/or positioning a substrate (306) or multiple substrates in the processing region (202b), wherein the substrate holding arrangement (104) has: a first drive train (312a) with a first substrate holder (304a), wherein the first substrate holder (304a) is configured to rotatably hold one or more substrates (306), a second drive train (312b) with a first support arm (302a), wherein the first substrate holder (304a) is held rotatably by the first support arm (302a), a third drive train (312c) with a second substrate holder (304b), wherein the second substrate holder (304b) is configured for rotatably holding one or more substrates (306), and a fourth drive train (312d) with a second support arm (302b), wherein the second substrate holder (304b) is held rotatably by the second support arm (302b), and wherein the first, second, third and fourth drive trains (312a, 312b, 312c, 312d) are each configured to be controllable independently of one another.

Figure 3B